

REMARKS

The Office Action dated April 23, 2003 has been received and carefully studied.

The Examiner rejects claims 6, 18 and 19 under 35 U.S.C. §112, second paragraph as being indefinite.

By the accompanying amendment, claim 6 has been amended by inserting the term "of" after "each". Regarding claim 18, by the accompanying amendment the Examiner's recommendation to delete "having" has been adopted.

The Examiner rejects claims 1-19 under 35 U.S.C. §112, first paragraph, because the specification does not reasonably provide enablement for products wherein the anhydride is used such that the resulting polyester lacks hydroxyl groups or carboxyl groups and the polyisocyanate is used such that the urethane prepolymer is hydroxyl terminated.

By the accompanying amendment, the claims have been amended to be commensurate in scope with the enablement provided in the specification.

The Examiner rejects claims 1-4 under 35 U.S.C. §102(b) as being anticipated by Chiang et al., U.S. Patent No. 4,935,535.

By the accompanying amendment, claims 1-4 have been cancelled.

Reconsideration and allowance are respectfully requested in view of the foregoing.

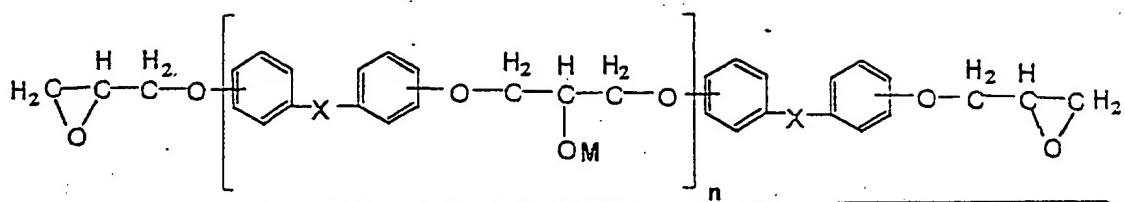
Respectfully submitted,



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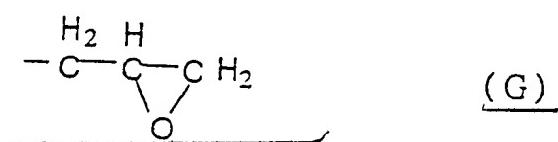
Listing of Claims

1. (Cancelled))
2. (Cancelled)
3. (Cancelled)
4. (Cancelled)
5. (Currently amended) A resin composition comprising a urethane oligomer (A) ~~according to claim 1 or the salt thereof, wherein the urethane oligomer (A) or the salt thereof is produced by reacting a polyol compound (a) with a polybasic acid anhydride (b-1) having at least two acid anhydride groups per molecule to produce the terminal alcohol compound having at least two carboxyl groups, subsequently reacting the product thereof with a polyisocyanate compound (c) to form a carboxyl group-containing terminal isocyanate urethane prepolymer and reacting said urethane prepolymer with a hydroxy compound having ethylenically unsaturated groups, and an unsaturated group-containing polycarboxylic acid resin (B) that is a product obtained by reacting an epoxy resin (e) having at least two epoxy groups per molecule with a monocarboxylic acid compound (f) having ethylenically unsaturated groups and a polybasic acid anhydride (b-2).~~
6. (Currently amended) A resin composition according to Claim ~~5~~ 5, wherein said epoxy resin (e) having at least two epoxy groups per molecule is represented by the Formula (1):



(1)

(In the formula, X is $-\text{CH}_2-$ or $-\text{C}(\text{CH}_3)_2-$, n is an integer of 1 or more, and M is hydrogen or a group represented by Formula (G) as shown below:



, provided that M is a group represented by Formula (G) if n is 1, while at least one M is a group represented by Formula (G) and each of the remainders being hydrogen if n is an integer of more than 1).

7. (Currently amended) A resin composition comprising a urethane oligomer (A) according to claim 4 5 and a thermoplastic polymer (D).
8. (Previously amended) A resin composition according to claim 5, comprising a diluent (C).
9. (Previously amended) A resin composition according to claim 5, further comprising a diluent (C), and wherein said diluent (C) is a reactive diluent (C-1).
10. (Previously amended) A resin composition according to claim 5 comprising a photopolymerization initiator (E).
11. (Currently amended) A resin composition comprising a urethane oligomer (A) according

to claim ~~4~~ 5, a thermoplastic polymer (D) and a photopolymerization initiator (E).

12. (Currently amended) A resin composition according to Claim ~~11~~ 11, wherein said thermoplastic polymer (D) is a polymer having carboxyl groups.

13. (Previously amended) A resin composition according to claim 5 comprising a thermoplastic component (F).

14. (Previously amended) A resin composition according to claim 5, wherein said resin composition is prepared for the solder resist in a printed circuit board or for an interlayer dielectric layer.

15. (Previously amended) A photosensitive film comprising being prepared by laminating the layer of a resin composition according to claim 5 on a supporting film.

16. ((Currently amended) A photosensitive film according to Claim ~~15~~ 15, wherein said photosensitive film is prepared for a printed circuit board.

17. (Previously amended) A cured product of the resin composition according to claim 5.

18. (Currently amended) An article comprising ~~having~~ the layer of a cured product according to claim ~~(17)~~ 17.

19. (Currently amended) An article according to Claim ~~(18)~~ 18, wherein said article is a printed circuit board.

20. (Cancelled)